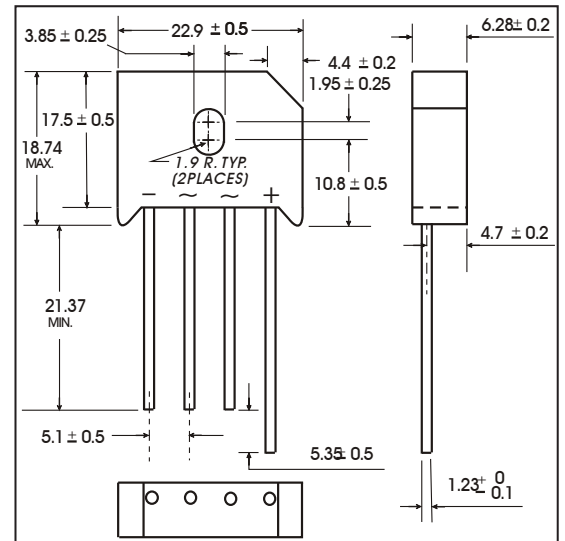


**KBU SILICON BRIDGE RECTIFIERV**
**Features**

- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low forward voltage drop
- High surge current capability
- Low reverse leakage current
- High temperature soldering guaranteed 265°C/10 seconds at 5 lbs (2.3kg) tension

**Mechanical Data**

- Case style:KBU molded plastic
- Mounting position:any


**MAXIMUM RATINGS AND CHARACTERISTICS**

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	KBU 10005	KBU 1001	KBU 1002	KBU 1004	KBU 1006	KBU 1008	KBU 1010	unit
Maximum repetitive peak reverse voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS bridge input voltage	VRMS	35	70	140	280	420	560	700	v
Maximum DC blocking voltage	VDC	50	100	200	400	600	800	1000	v
Maximum average forward rectified output current at TA=100°C	IF(AV)	10							A
Peak forward surge current single sine-wave superimposed on rated load (JEDEC Method)	IFSM	300							A
Rating for fusing ( t<8.3ms)	I <sup>2</sup> t	300							A <sup>2</sup> sec
Typical thermal resistance per element (1)	ReJA	2.7							°C / W
Operating junction and storage temperature range	TJ TSTG	-55 to +150							°C
Maximum instantaneous forward voltage drop per leg at 10A	VF	1.05							V
Maximum DC reverse current at rated TA =25°C DC blocking voltage per element TA =125°C	IR	10 500							uA

**Notes:** (1)Thermal resistance from Junction to Ambient on P.C.board mounting.

RATINGS AND CHARACTERISTIC CURVES

Fig. 1 Derating Curve for Output Rectified Current

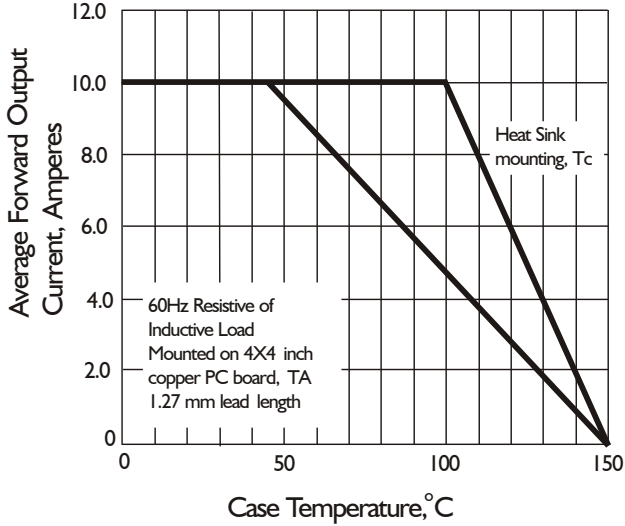


Fig. 2 Maximum Non-repetitive Peak Forward Surge Current

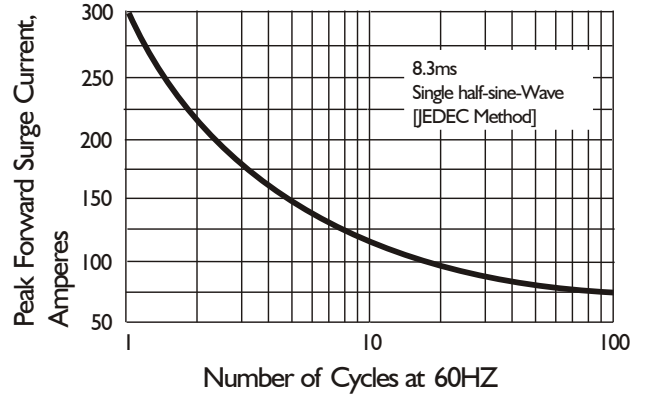


Fig. 3 Typical Instantaneous Forward Characteristics

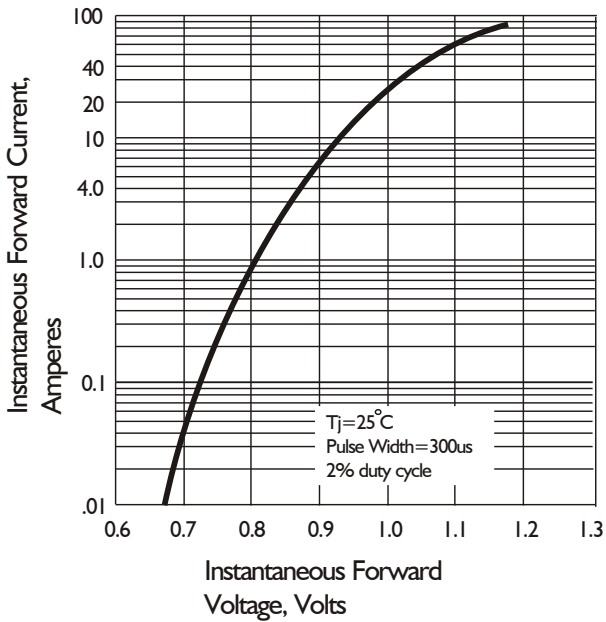


Fig. 4 Typical Reverse Characteristics

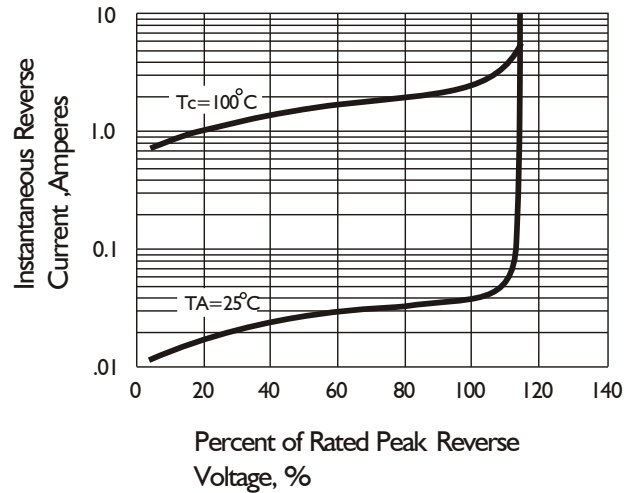


Fig. 5 Typical Junction Capacitance

